



Material Content Data Sheet



Halogen-Free

Sales Product Name	ISC0803NLS	Issued	23. June 2021
MA#	MA005432740		
Package	PG-TDSON-8-51	Weight*	101.48 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.358	0.35	0.35	3532	3532
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		134	
	non noble metal	zinc	7440-66-6	0.055	0.05		537	
	non noble metal	iron	7439-89-6	1.090	1.07		10744	
	non noble metal	copper	7440-50-8	44.271	43.64	44.77	436260	447675
wire	noble metal	gold	7440-57-5	0.035	0.03	0.03	340	340
encapsulation	organic material	carbon black	1333-86-4	0.089	0.09		873	
	plastics	epoxy resin	-	4.077	4.02		40172	
	inorganic material	silicondioxide	60676-86-0	40.146	39.56	43.67	395609	436654
leadfinish	non noble metal	tin	7440-31-5	1.264	1.25	1.25	12453	12453
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	286	286
solder	noble metal	silver	7440-22-4	0.014	0.01		138	
	non noble metal	tin	7440-31-5	0.028	0.03		276	
	non noble metal	lead	7439-92-1	0.518	0.51	0.55	5109	5523
heat sink clip	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	zinc	7440-66-6	0.011	0.01		112	
	non noble metal	iron	7439-89-6	0.228	0.22		2245	
	non noble metal	copper	7440-50-8	9.250	9.12	9.35	91152	93537
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com